Preferred Device

Silicon Controlled Rectifiers

Reverse Blocking Thyristors

Designed for inverse parallel SCR output devices for solid state relays, welders, battery chargers, motor controls or applications requiring high surge operation.

- Photo Glass Passivated Blocking Junctions for High Temperature Stability, Center Gate for Uniform Parameters
- 550 Amperes Surge Capability
- Blocking Voltage to 800 Volts
- Device Marking: Logo, Device Type, e.g., MCR265-4, Date Code

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off–State Voltage ⁽¹⁾ (T _J = 25 to 125°C, Sine Wave, 50 to 60 Hz, Gate Open) MCR265–4 MCR265–6	VDRM, VRRM	200 400	Volts
MCR265-8 MCR265-10		600 800	
On-State RMS Current (180° Conduction Angles; T _C = 70°C)	IT(RMS)	55	Amps
Average On-State Current (180° Conduction Angles; T _C = 70°C)	I _{T(AV)}	35	Amps
Peak Non-Repetitive Surge Current (1/2 Cycle, Sine Wave, 60 Hz, T _J = 70°C)	ITSM	550	Amps
Forward Peak Gate Power (Pulse Width ≤ 1.0 μs, T _C = 70°C)	Рдм	20	Watts
Forward Average Gate Power (t = 8.3 ms, T _C = 70°C)	PG(AV)	0.5	Watt
Forward Peak Gate Current (Pulse Width ≤ 1.0 μs, T _C = 70°C)	I _{GM}	2.0	Amps
Operating Junction Temperature Range	TJ	-40 to +125	°C
Storage Temperature Range	T _{stg}	-40 to +150	°C

(1) V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

These devices are rated for use in applications subject to high surge conditions. Care must be taken to insure proper heat sinking when the device is to be used at high sustained currents.

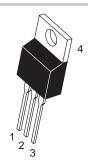


ON Semiconductor

http://onsemi.com

SCRs 55 AMPERES RMS 200 thru 800 VOLTS





TO-220AB CASE 221A STYLE 3

PIN ASSIGNMENT				
1	Cathode			
2	Anode			
3	Gate			
4	Anode			

ORDERING INFORMATION

Device	Package	Shipping
MCR265-4	TO220AB	500/Box
MCR265-6	TO220AB	500/Box
MCR265-8	TO220AB	500/Box
MCR265-10	TO220AB	500/Box

Preferred devices are recommended choices for future use and best overall value.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{ heta JC}$	0.9	°C/W
Thermal Resistance, Junction to Ambient	$R_{ heta JA}$	60	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	T∟	260	°C

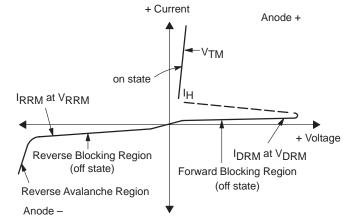
ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted.)

Symbol	Min	Тур	Max	Unit
•				
I _{DRM} , I _{RRM}	_	_	10 2.0	μA mA
				-
Vтм	_	1.5	1.9	Volts
l _{GT}	_	20 40	50 90	mA
VGT	_	1.0	1.5	Volts
V _{GD}	0.2	_	_	Volts
lн	_	30	75	mA
tgt	_	1.5	_	μs
			-	
dv/dt	_	50	_	V/μs
	VTM IGT VGD IH tgt	VTM	IDRM, IRRM	IDRM, IRRM

⁽¹⁾ Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.

Voltage Current Characteristic of SCR

Symbol	Parameter
VDRM	Peak Repetitive Off State Forward Voltage
IDRM	Peak Forward Blocking Current
VRRM	Peak Repetitive Off State Reverse Voltage
I _{RRM}	Peak Reverse Blocking Current
V_{TM}	Peak On State Voltage
lΗ	Holding Current



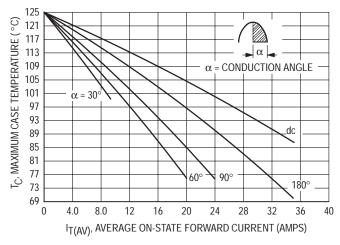


Figure 1. Average Current Derating

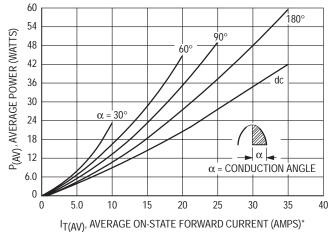


Figure 2. Maximum On-State Power Dissipation

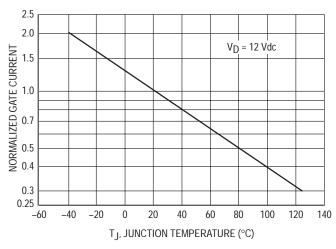


Figure 3. Typical Gate Trigger Current

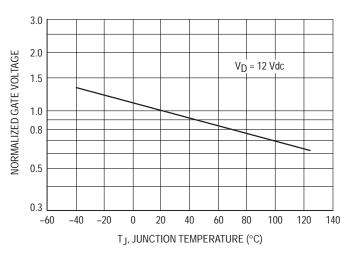


Figure 4. Typical Gate Trigger Voltage

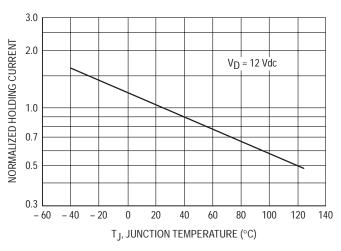


Figure 5. Typical Holding Current

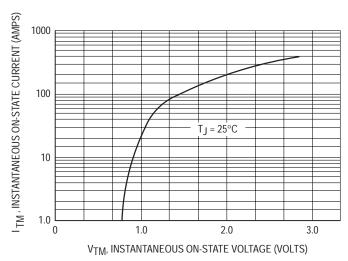


Figure 6. Typical On-State Characteristics

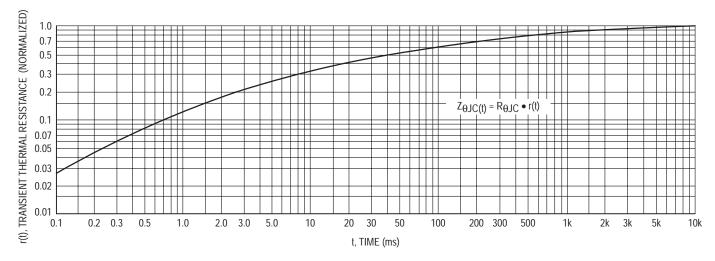
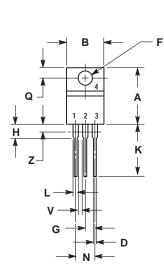
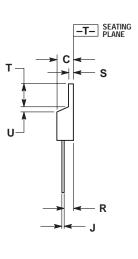


Figure 7. Thermal Response

PACKAGE DIMENSIONS

TO-220AB CASE 221A-07 ISSUE Z





- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.014	0.022	0.36	0.55
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	
Z		0.080		2.04

- STYLE 3:
 PIN 1. CATHODE
 2. ANODE
 3. GATE
 4. ANODE

Notes



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